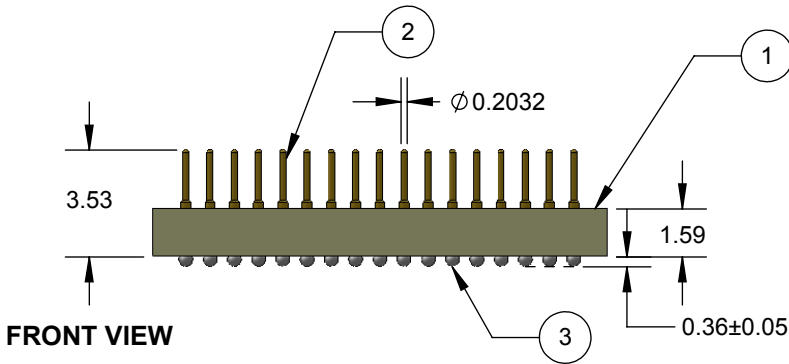


TOP VIEW



FRONT VIEW

PART NO. SUFFIX	SOLDER BALL ALLOY
-61	Sn63Pb37
-61F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material; Non-clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- ③ Solder Balls: See Table.

Description: Giga-SnaP BGA foot, 17x17 array, 0.8mm pitch 15mm sq.

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0254mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA256K-B-61 Specification		MATERIAL: N/A FINISH: N/A WEIGHT: 0.90	STATUS: Released	SHEET 1 OF 1	REV. A
SF-BGA256K-B-61F Specification					
	Ironwood Electronics, Inc.		ENG: S. Faiz	Drawn By: D. Hauer	
	Tele: (800) 404-0204		File: SF-BGA256K-B-61	DATE: 12/09/13	SCALE: 4:1
	www.ironwoodelectronics.com				